



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			


Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-05-16
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.

Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
<b>Legal Statement</b>	<p>Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.</p>		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STPS3L40UF	7N6Y*Z67Q83Y	A	ZA41	2016-05-16
	Amount	UoM	Unit type	ST ECOPACK Grade
	50.00	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SMC	4.3 - 3.75 - 1	2	flat	
Comment	Package: SMB Flat NEP			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7N6Y*Z67Q83Y									
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	Other inorganic materials	1.497	mg	supplier	die	Silicon (Si)	7440-21-3		1.241	mg	828991	24820				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.060	mg	40080	1200				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	668	20				
				supplier	metallization	Tungsten (W)	7440-33-7		0.002	mg	1336	40				
				supplier	metallization	Nickel (Ni)	7440-02-0		0.007	mg	4676	140				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.009	mg	6012	180				
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.001	mg	669	20				
				supplier	back side metallization	Gold (Au)	7440-57-5		0.002	mg	1336	40				
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.010	mg	6680	200				
				supplier	polymer die coating	Durimide	proprietary		0.164	mg	109552	3280				
				Lead-frame & Clip	Copper & its alloys	24.139	mg	Supplier	Alloy	Copper (Cu)	7440-50-8		24.108	mg	998716	482160
								Supplier	Alloy	Iron (Fe)	7439-89-6		0.024	mg	994	480
								Supplier	Alloy	Phosphorus (P)	12185-10-3		0.007	mg	290	140
Die Attach	Solder	2.769	mg	Supplier	soft solder	Silver (Ag)	7440-22-4		0.070	mg	25280	1400				
				Supplier	soft solder	Tin (Sn)	7440-31-5		0.138	mg	49837	2760				
				Supplier	R	Lead (Pb)	7439-92-1	7a-Lead in high me	2.561	mg	924883	51220				
Encapsulation	Other inorganic materials	20.725	mg	Supplier	Molding Compound	Silica , amorphous,fused	60676-86-0		17.194	mg	829626	343880				
				Supplier	Molding Compound	Epoxy resin propietare,resin unknown	29690-82-2		2.787	mg	134475	55740				
				Supplier	Molding Compound	Benzophenone teracarboxylic anhydride	2421-28-5		0.114	mg	5501	2280				
				Supplier	Molding Compound	Silica, quartz	14808-60-7		0.516	mg	24897	10320				
				Supplier	Molding Compound	Carbon black	1333-86-4		0.114	mg	5501	2280				
Connections coating	Solder	0.870	mg	Supplier	connection coating	Tin (Sn)	7440-31-5		0.870	mg	1000000	17400				